

**Amendments to the Specification:**

- Please replace the Title of the Application with the following amended Title:

~~Electronic Module Design to Maximize the Volume Efficiency in a Miniature Medical Device~~  
Method of Making an Electronic Module

- Please replace paragraph [0056] with the following amended paragraph:

[0056] As seen, e.g., in FIGS. 1B, 5 and 10A, the top and bottom of substrate panel assembly 202n are used to mount other components. As examples, the bottom face 701 (shown in FIGS. 6A and 6B) of an integrated circuit 206 is mounted to the top 204 of each substrate panel 202 and capacitor 208B1, 208B2 are mounted to the bottom 205 of each substrate panel. All the off-chip, or secondary, components are electrically connected to IC 206 through substrate 202 or through redistributed surface 720, as described below.